

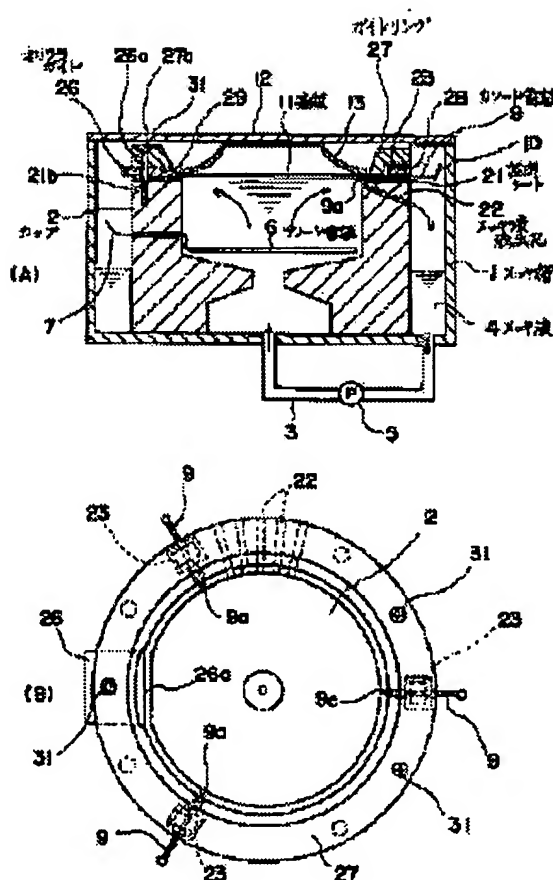
PLATING DEVICE AND METHOD AND SUBSTRATE TO BE PLATED

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Abstract of JP7211724

PURPOSE:To make possible the full contact between a cathode electrode and a plating solution to be avoided, furthermore, the assured conductive state by sufficient bonding power between the cathode electrode and a substrate.

CONSTITUTION:Outlet holes 22 for passing plating solution are provided radially in the peripheral wall upper part of a cup 2 jetting the plating solution 4 while a circular sealing seat 21 made of an elastic material e.g. rubber, etc., is provided on the surface of the peripheral wall part. Furthermore, a linear cathode electrode 9 made of Pt wire, etc., is provided on the surface of this sealing seat 21 in the state of electrode 9 with the end positioned outside the inner peripheral surface at a specific distance. Besides, almost the periphery of the plated surface of the substrate 11 is brought into close contact with the surface of the sealing seat 21 in the state of the connecting terminal for plating the substrate 11 in contact with the linear cathode electrode 9 by such means as a spring seat pressing down the substrate 11 or a weight loaded upon the substrate 11, etc.



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